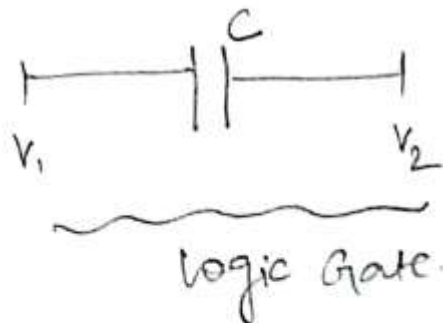


## MOS transistor - C-V characteristics.

→ Capacitances are Non Linear and voltage dependent. (C-V).

→ Simple capacitors approximated, when its behaviour is averaged across switching voltages of a logic gate.



$$\frac{V_1 + V_2}{2} = \dot{C}' \text{ behavior}$$

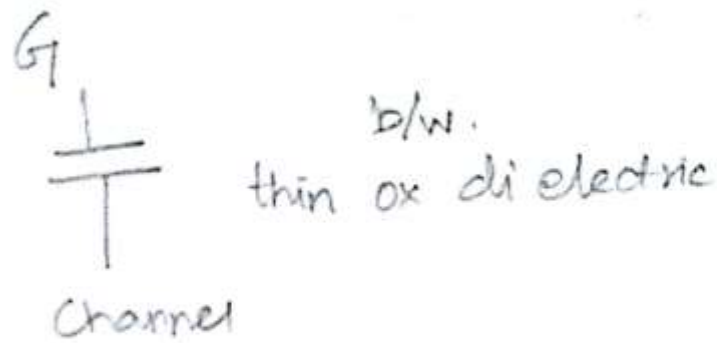
→ To estimate delay and Power consume of transistors.

- 1\* Simple MOS Capacitance Models.
- 2\* Detailed MOS Gate Capacitance Model
- 3\* Detailed MOS diffusion Capacitance Model.

1\*

↳ MOS - G1  $\Rightarrow$  good capacitor.

↳ To attract charge to invert channel  
Hi capacitance needed to get hi  $I_{ds}$ .



So,  $C_g = C_{ox} WL$  — (1)

\* Capacitor is a 2 terminal device.

\* When transistor ON  $\rightarrow$  channel extends from source & reach drain. (S)  $\rightarrow$  (D)  
 $\hookrightarrow$  'in sat'.  
 or stops short in 'sat'.

\* Most transistor used min. manufacturable 'L'  
 great speed & low power consume.

$C_g = C_{perm} \cdot w$  — (2)

$C_{perm} = C_{ox} \cdot L = \frac{\epsilon_{ox}}{t_{ox}} \cdot L$  — (3)

\*  $C_g, C_D, C_S \rightarrow$  make impact ext. performance  
 so It is called "Parasitic Capacitors"

\* It arises from reverse biased P-n Jn.

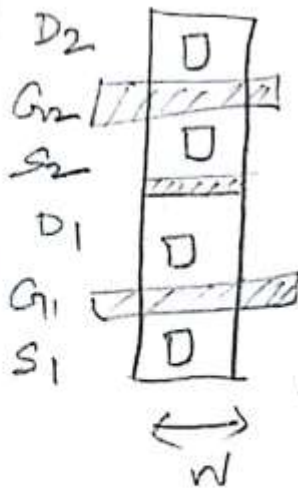
b/w (S)/(D) diffusion & body/substrate(b)

It is called "diffusion capacitances"  
 $C_{sb}, C_{db}$

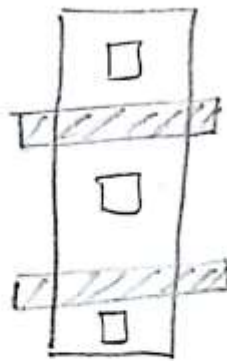
C-V . . . .

The size of these jn. depends on Area, and perimeter of  $\text{S}$ ,  $\text{D}$  diffusion, depth of diffusion, doping levels &  $\text{V}$ .  
So, diffusion has High  $\underline{C}$  &  $\underline{R}$

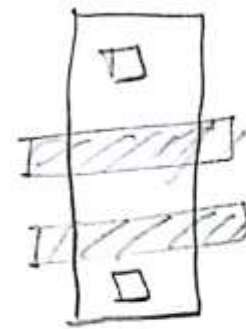
Diffusion region geometries:



isolated



Shared



Merged

2\* Detailed MOS Gate Capacitance Model.

MOS gate sits above channel & parallel overlap  $\text{S}$  &  $\text{D}$ .

- Intrinsic capacitance (over the channel)
- Overlap capacitance ( $\text{S}$ ,  $\text{D}$ ,  $\text{B}$ ).

$$C_0 = WL C_{ox}$$

Cutoff:-

When transistor is off ( $V_{gs} = 0$ ) channel is not inverted and charge on gate is matched with opposite charge from body.

$C_{gb} \rightarrow$  gate to body capacitance.

$V_{gs} < V_t \rightarrow$  depletion forms at surface. bottom plate moves downward from 'ox' reducing capacitance.

Linear.  $V_{gs} > V_t$  channel inverts and again serves good conductive bottom plate. However ch- is connected to (S) & (D) rather than (B). \* At low  $V_{ds}$  the channel charge shared b/w (S)  $\frac{1}{2}$  (D)

$$C_{gs} = C_{gd} = C_0/2$$

\* As  $V_{ds}$  increases the region near (D) less inverted, so greater fraction of  $i_c$  attributed to (S) & small fraction to (D).

Sat :-  $V_{ds} > V_{gs} - V_t$  channel-pinch-off

All intrinsic  $i_c$  is to (S).

$$C_{gs} = \frac{2}{3} C_0$$

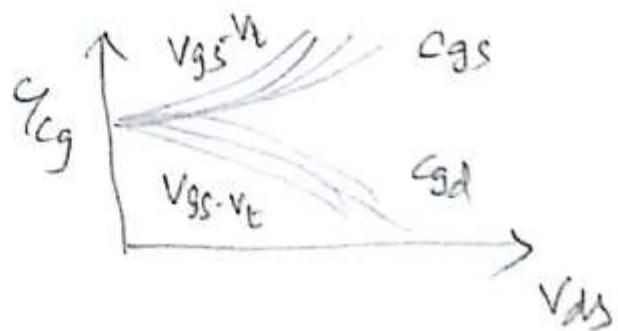
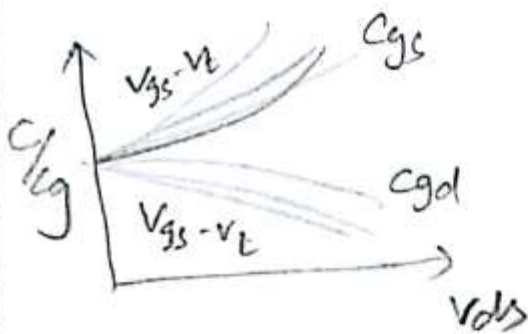
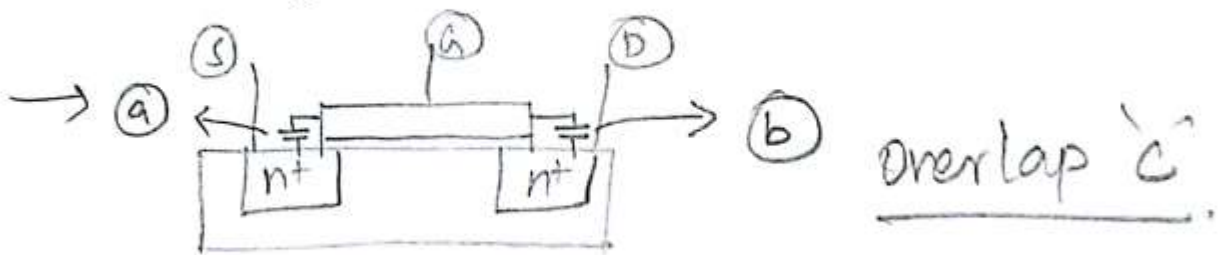
	cutoff	Linear	Sat
$C_{gb}$	$C_0$	0	0
$C_{gs}$	0	$C_0/2$	$2/3 C_0$
$C_{gd}$	0	$C_0/2$	0
$C_g = C_{gb} + C_{gs} + C_{gd}$	$C_0$	$C_0$	$2/3 C_0$

$$C_g = C_{gb} + C_{gs} + C_{gd} \sim C_0$$

→

(a)  $C_{gs} \text{ (overlap)} = C_{gsd} \cdot W$

(b)  $C_{gd} \text{ (overlap)} = C_{gdol} \cdot W$



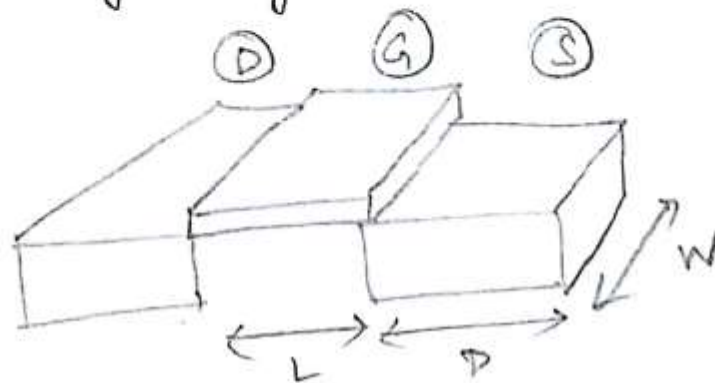
↓  
 $C \rightarrow$  vary as a fn. of  $V_{ds}$  for no. of  $V_{gs} - V_t$

↓  
 Short-ch. transition:  
 $C_{gd} \neq 0 \rightarrow$  sat

$C_g \rightarrow$  charge based model  
 $C_{gd} \text{ (overlap)} \rightarrow$  signif. - cant  
 Overlap  $\rightarrow$  voltage dependence. for delay cal.

### 3\* Detailed MOS diffusion capacitance Model.

Diffusion region geometry.



$$AS = W \cdot D \quad PS = 2W + 2D$$

Total source parasitic 'C'.

$$C_{sb} = AS \cdot \underbrace{C_{jbs}}_{\substack{\leftarrow \text{unit} \\ \text{C/Area}}} + PS \cdot \underbrace{C_{jbs}}_{\substack{\text{C/Length}}} \quad \text{--- (1)}$$

\* depletion region thickness dep. reverse bias.  
So it's non linear.

$$C_{jbs} = C_j \left( 1 + \frac{V_{sb}}{\phi_0} \right)^{-M_j}$$

$C_j \rightarrow$  Jn. capacitance at zero bias & high process dependent.

$M_j \rightarrow$  Junction grading coefficient.

$$= 0.5 - 0.33$$

$\phi_0 \rightarrow$  built in potential dep. on doping level.

$$\psi_0 = V_T \ln \frac{N_A \cdot N_D}{n_i^2}$$

$V_T$  → thermal voltage from thermodynamics

Side wall capacitance.

$$C_{jbsw} = C_{jsw} \left( 1 + \frac{V_{sb}}{\psi_0} \right)^{-M_{jsw}}$$

$$C_{jbswg} = C_{jswg} \left( 1 + \frac{V_{sb}}{\psi_0} \right)^{-M_{jswg}}$$

Drain diffusion has  $111\%$  parasitic  $C'$  dep. on  $A_D$ ,  $P_D$  &  $V_{db}$ .

Value averaged across switching transition.

Diffusion regions used for short wires called "runners"

MOS transistor → 4 terminal device

$C_{G1}$  → intrinsic component (to body, (S), & (D) (on (S) alone dep. on operating regime).

